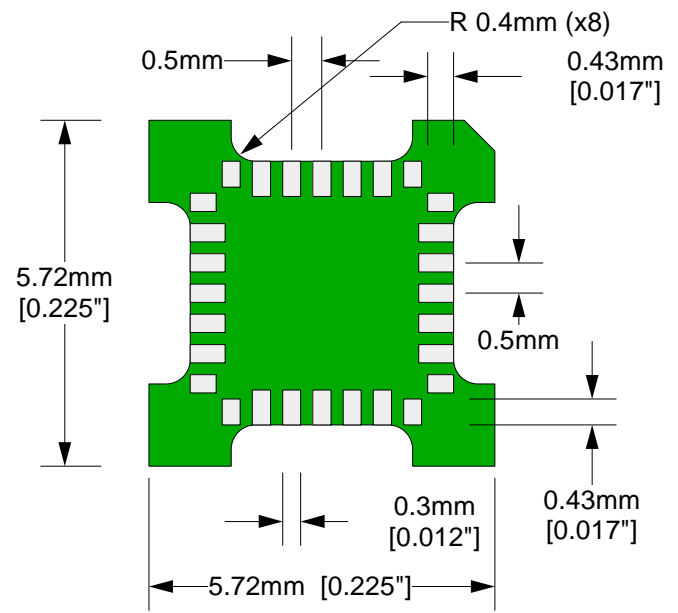


Top View

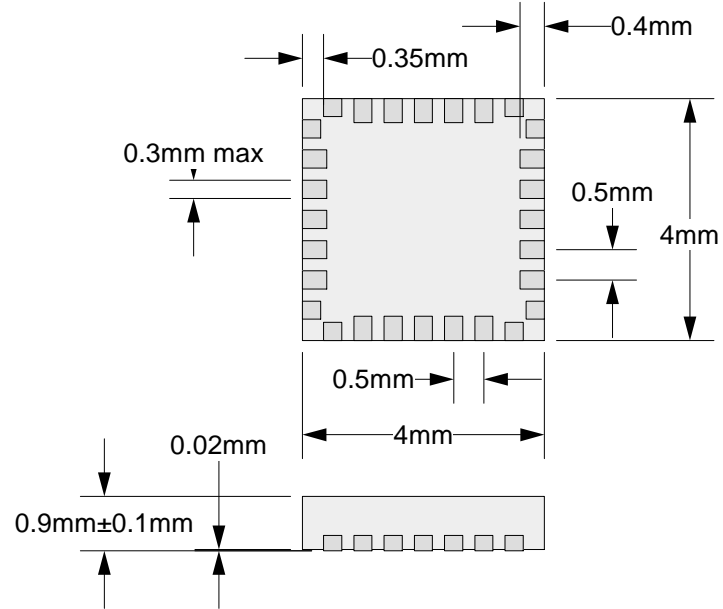


Bottom View

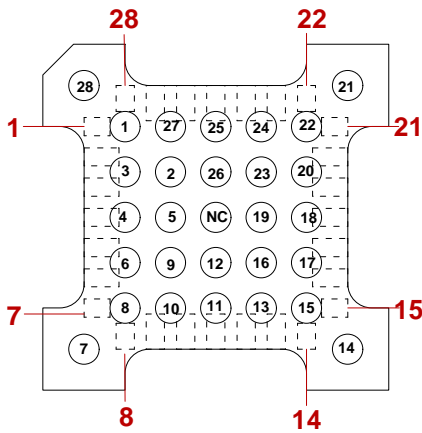


Side View

Compatible IC



Pinout




Top View

- ① Substrate: 0.79mm ±0.18mm [0.031" ±0.007"]
IPC 4101/21 material. RoHS finish.
- ② Substrate: 1.59mm ±0.18mm [0.062" ±0.007"]
IPC 4101/21 material. Non-clad.
- ③ Pins: shell material- Brass Alloy 360 1/2 hard;
finish- 0.25µm [10µ"] Au over 1.27µm [50µ"]
Ni (min.). Contact material- BeCu; finish
0.25µm [10µ"] Au over 2.54µm [100µ"] Ni
(min.).

Description: MLF surface mount foot (SF) 28 position female micro grid array (UGA) to 28 position(+4 GND) MLF SMT interface. Part solders to target board land using standard industry SMT techniques.



Tolerances: diameters ±0.03mm [±0.001"], PCB perimeters ±0.13mm [±0.005"], PCB thicknesses ±0.18mm [±0.007"], pitches (from true position) ±0.08mm [±0.003"], all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

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	<p>Drawing: E Smolentseva</p>		<p>Date: 3/3/10</p>	
	<p>File: SF-QFN28F-A-02F Dwg.mcd</p>		<p>Modified:</p>	